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## PMP11438 REV A Bill of Materials



Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C7	2	0.047uF	GRM155R61A473KA01D	MuRata	CAP, CERM, 0.047 µF, 10 V, +/- 10%, X5R, 0402	0402
C2, C3	2	10uF	GRM188R61E106MA73	MuRata	CAP, CERM, 10 µF, 25 V, +/- 20%, X5R, 0603	0603
C4, C30, C37	3	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
C5, C25, C31	3	100uF	293D107X9020E2TE3	Vishay-Sprague	CAP, TA, 100uF, 20V, +/-10%, 0.5 ohm, SMD	7343-43
C6	1	1uF	GRM31MR71H105KA88L	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 1206	1206
C8, C9, C33, C34,	8	47uF	GRM21BR61A476ME15	MuRata	CAP, CERM, 47 μF, 10 V, +/- 20%, X5R, 0805	0805
C35, C36, C40, C41					·	
C10, C11, C21, C22, C23, C24	6	DNP	GRM21BR61A476ME15	MuRata	CAP, CERM, 47 μF, 10 V, +/- 20%, X5R, 0805	0805
C12, C13	2	DNP	GRM188R60J226MEA0J	MuRata	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0603	0603
C14, C26	2	470pF	GRM1555C1H471JA01D	MuRata	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C15	1	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0603	0603
C16	1	1uF	C1005X5R1C105K050BC	TDK	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0402	0402
C17, C18	2	470uF	2TPE470MAJGB	Panasonic	CAP, Tantalum Polymer, 470 µF, 2 V, +/- 20%, 0.011 ohm,	3.5x1.9x2.8mm
					3.5x1.9x2.8mm SMD	
C19, C20, C28, C29	4	22uF	C3216X5R1E226M160AB	TDK	CAP, CERM, 22 μF, 25 V, +/- 20%, X5R, 1206_190	1206_190
C27	1	3300pF	GRM155R71H332KA01D	MuRata	CAP, CERM, 3300 pF, 50 V, +/- 10%, X7R, 0402	0402
C32	1	470pF	C1005X7R1H471K	TDK	CAP, CERM, 470 pF, 50 V, +/- 10%, X7R, 0402	0402
C38	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7uF, 16V, +/-10%, X5R, 0603	0603
C39	1	1uF	GRM188R61H105KAALD	MuRata	CAP, CERM, 1 µF, 50 V, +/- 10%, X5R, 0603	0603
C42, C43	2	22uF	GRM188R60J226MEA0J	MuRata	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0603	0603
J1, J2, J3, J4, J5, J6	6		OSTTE020161	On-Shore Technology	Terminal Block, 2x1, 3.5mm, TH	2x1 Terminal Block
L1	1	220nH	PIFE32251B-R22MS	Cyntec	Inductor, Drum Core, Powdered Iron, 220 nH, xx A, xxx ohm, SMD	Inductor, 3.2x1.2x2.5mm
L2	1	220nH		Cyntec	Inductor, Drum Core, Powdered Iron, 220 nH, xx A, xxx ohm, SMD	Inductor, 3.2x1.2x2.5mm
L3, L4	2	1uH	DFE252012F-1R0M	Toko	Inductor, Shielded, 1 µH, 3.3 A, 0.040 ohm	1008
L5	1	680nH	PIMB065T-R68	Cyntec	Inductor, Drum Core, Ferrite, 680 nH, 18 A, 0.0042 ohm, SMD	7.05x4.8x6.6mm
Q1, Q2, Q3	3	25V	CSD16410Q5A	Texas Instruments	MOSFET, N-CH, 25 V, 59 A, SON 5x6mm	SON 5x6mm
R1, R14, R27	3	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R2, R15	2	475k	CRCW0402475KFKED	Vishay-Dale	RES, 475 k, 1%, 0.063 W, 0402	0402
R3	1	1.00k	CRCW04021K00FKED	Vishav-Dale	RES, 1.00 k, 1%, 0.063 W, 0402	0402
R4, R13, R19	3	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R5, R20, R21, R30	4	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0, 5%, 0.063 W, 0402	0402
R6	1	750	CRCW0402750RFKED	Vishay-Dale	RES, 750, 1%, 0.063 W, 0402	0402
R7	1	DNP	CRCW0402730KFKED	Vishay-Dale Vishay-Dale	RES, 47.5 k, 1%, 0.063 W, 0402	0402
R8	1	150k	CRCW040247K5FKED	Vishay-Dale Vishay-Dale	RES, 150 k, 1%, 0.063 W, 0402	0402
R9	1	DNP	CRCW0402130KFKED	Vishay-Dale Vishay-Dale	RES, 150 K, 1%, 0.063 W, 0402 RES, 22.1 k, 1%, 0.063 W, 0402	0402
R10	1	24.9k	CRCW040222KTFKED	Vishay-Dale Vishay-Dale	RES, 24.9 k, 1%, 0.063 W, 0402	0402
R11, R17, R34	3	10.0k	CRCW040224K9FKED	Vishay-Dale Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R11, R17, R34 R12, R18, R35	3	0.032	WSL2512R0320FEA18	Vishay-Dale Vishay-Dale	RES, 10.0 K, 1%, 0.1 W, 0603 RES, 0.032, 1%, 2 W, 2512	2512
R16, R22	2	200k	CRCW0402200KFKED	- 1	RES, 0.032, 1%, 2 W, 2512 RES, 200 k, 1%, 0.063 W, 0402	0402
,		3.01		Vishay-Dale		0805
R23	1		CRCW08053R01FKEA	Vishay-Dale	RES, 3.01, 1%, 0.125 W, 0805	
R24, R28	2	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R25	1	DNP	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R26	1	DNP	CRCW0402187KFKED	Vishay-Dale	RES, 187 k, 1%, 0.063 W, 0402	0402
R29	1	240k	CRCW0402240KFKED	Vishay-Dale Page	ge 1RES, 240 k, 1%, 0.063 W, 0402	0402

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R31	1	48.7k	CRCW040248K7FKED	Vishay-Dale	RES, 48.7 k, 1%, 0.063 W, 0402	0402
R32	1	71.5k	CRCW040271K5FKED	Vishay-Dale	RES, 71.5 k, 1%, 0.063 W, 0402	0402
R33	1	32.4k	CRCW040232K4FKED	Vishay-Dale	RES, 32.4 k, 1%, 0.063 W, 0402	0402
TP1, TP3, TP7,	6	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
TP8, TP13, TP14						Testpoint
TP2, TP6, TP9,	6	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
TP12, TP16,						Testpoint
TP18						
TP4, TP5, TP10,	6	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature
TP11, TP15,						Testpoint
TP17						
U1	1		TPS54A20RNJR	Texas Instruments	10A/14V Series Capacitor Buck Converter, RNJ0020A	RNJ0020A
U2	1		TPS62184YZFR	Texas Instruments	4-V to 17-V, 6-A, 2-Phase Step-Down Converter with AEE,	YZF0024AMAM
					YZF0024AMAM	
U3	1		TPS53515RVER	Texas Instruments	High Performance, 12-A Single Synchronous Step-Down Converter,	RVE0028A
					RVE0028A	

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